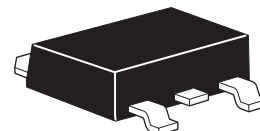


# ZXMP10A16K

## 100V DPAK P-channel enhancement mode MOSFET

### Summary

$V_{(BR)DSS}$	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
-100	0.235 @ $V_{GS} = -10V$	4.6
	0.285 @ $V_{GS} = -6V$	4.2



### Description

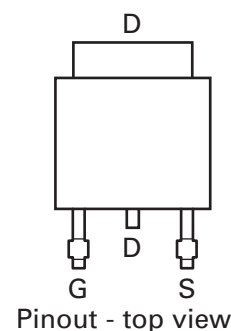
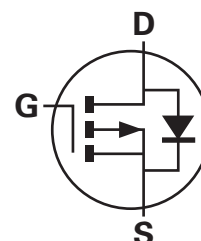
This new generation trench MOSFET from Zetex features a unique structure combining the benefits of low on-resistance and fast switching, making it ideal for high efficiency power management applications.

### Features

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- DPAK package

### Applications

- DC-DC converters
- Power management functions
- Disconnect switches
- Motor control



### Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMP10A16KTC	13	16	2500

### Device marking

ZXMP  
10A16

# ZXMP10A16K

## Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Drain-source voltage	$V_{DSS}$	-100	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current @ $V_{GS} = 10V$ ; $T_{amb} = 25^{\circ}C^{(b)}$	$I_D$	4.6	A
@ $V_{GS} = 10V$ ; $T_{amb} = 70^{\circ}C^{(b)}$		3.7	
@ $V_{GS} = 10V$ ; $T_{amb} = 25^{\circ}C^{(a)}$		3	
Pulsed drain current <sup>(c)</sup>	$I_{DM}$	15.4	A
Continuous source current (body diode) <sup>(b)</sup>	$I_S$	10.6	A
Pulsed source current (body diode) <sup>(c)</sup>	$I_{SM}$	15.4	A
Power dissipation at $T_{amb} = 25^{\circ}C^{(a)}$	$P_D$	4.24	W
Linear derating factor		34	mW/ $^{\circ}C$
Power dissipation at $T_{amb} = 25^{\circ}C^{(b)}$	$P_D$	9.76	W
Linear derating factor		78	mW/ $^{\circ}C$
Power dissipation at $T_{amb} = 25^{\circ}C^{(d)}$	$P_D$	2.15	W
Linear derating factor		16.8	mW/ $^{\circ}C$
Operating and storage temperature range	$T_j, T_{stg}$	-55 to +150	$^{\circ}C$

## Thermal resistance

Parameter	Symbol	Limit	Unit
Junction to ambient <sup>(a)</sup>	$R_{\theta JA}$	29.45	$^{\circ}C/W$
Junction to ambient <sup>(b)</sup>	$R_{\theta JA}$	12.8	$^{\circ}C/W$
Junction to ambient <sup>(d)</sup>	$R_{\theta JA}$	58.1	$^{\circ}C/W$

### NOTES:

(a) For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions.

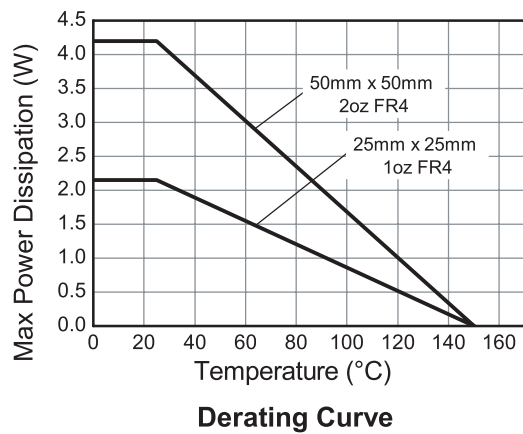
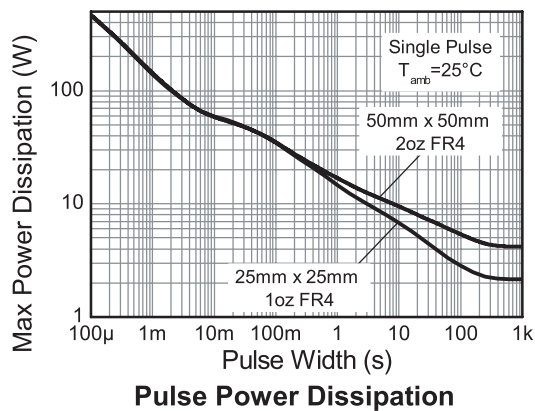
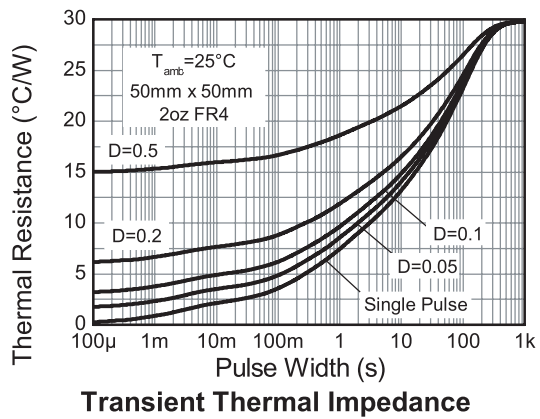
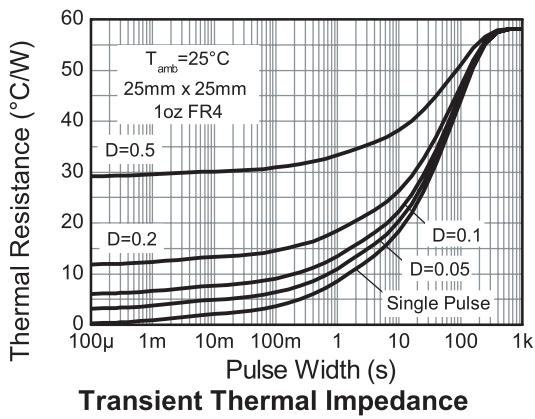
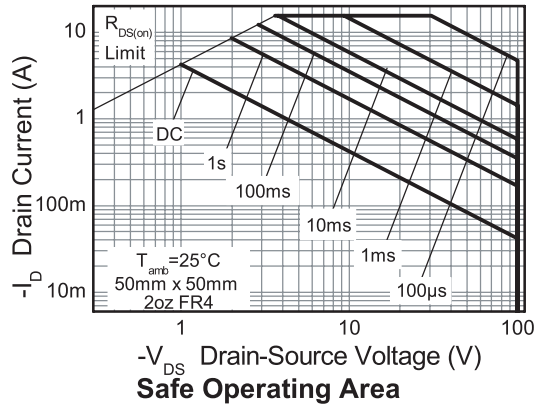
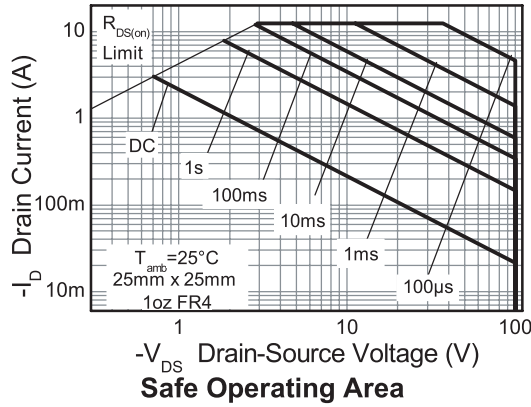
(b) For a device surface mounted on FR4 PCB measured at  $t \leq 10$  sec.

(c) Repetitive rating 50mm x 50mm x 1.6mm FR4 PCB,  $D=0.02$  pulse width=300 $\mu s$  - pulse width limited by maximum junction temperature.

(d) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

# ZXMP10A16K

## Typical characteristics



# ZXMP10A16K

## Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Static						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	-100			V	I <sub>D</sub> = 250μA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>			-1	μA	V <sub>DS</sub> = -100V, V <sub>GS</sub> =0V
Gate-body leakage	I <sub>GSS</sub>			100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
Gate-source threshold voltage	V <sub>GS(th)</sub>	-2.0		-4.0	V	I <sub>D</sub> = -250μA, V <sub>DS</sub> =V <sub>GS</sub>
Static drain-source on-state resistance <sup>(*)</sup>	R <sub>DS(on)</sub>			0.235 0.285	W	V <sub>GS</sub> = -10V, I <sub>D</sub> = -2.1A V <sub>GS</sub> = -6V, I <sub>D</sub> = -1.9A
Forward transconductance <sup>(*)</sup> (‡)	g <sub>fs</sub>		4.7		S	V <sub>DS</sub> = -15V, I <sub>D</sub> = -2.1A
Dynamic <sup>(‡)</sup>						
Input capacitance	C <sub>iss</sub>		717		pF	V <sub>DS</sub> = -50V, V <sub>GS</sub> =0V f=1MHz
Output capacitance	C <sub>oss</sub>		55.3		pF	
Reverse transfer capacitance	C <sub>rss</sub>		46.4		pF	
Switching <sup>(†)</sup> (‡)						
Turn-on-delay time	t <sub>d(on)</sub>		4.3		ns	V <sub>DD</sub> = -50V, I <sub>D</sub> = -1A R <sub>G</sub> =6.0Ω, V <sub>GS</sub> = -10V
Rise time	t <sub>r</sub>		5.2		ns	
Turn-off delay time	t <sub>d(off)</sub>		20		ns	
Fall time	t <sub>f</sub>		12.1		ns	
Total gate charge	Q <sub>g</sub>		16.5		nC	V <sub>DS</sub> = -50V, V <sub>GS</sub> = -10V I <sub>D</sub> = -2.1A
Gate-source charge	Q <sub>gs</sub>		2.47		nC	
Gate drain charge	Q <sub>gd</sub>		5.36		nC	
Source-drain diode						
Diode forward voltage <sup>(*)</sup>	V <sub>SD</sub>		-0.85	-0.95	V	T <sub>j</sub> =25°C, I <sub>S</sub> = -3.35A, V <sub>GS</sub> =0V
Reverse recovery time <sup>(‡)</sup>	t <sub>rr</sub>		43.3		ns	T <sub>j</sub> =25°C, I <sub>S</sub> = -2.4A, di/dt=100A/μs
Reverse recovery charge <sup>(‡)</sup>	Q <sub>rr</sub>		76.5		nC	

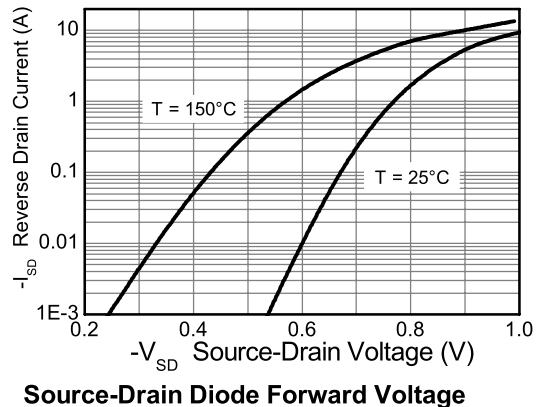
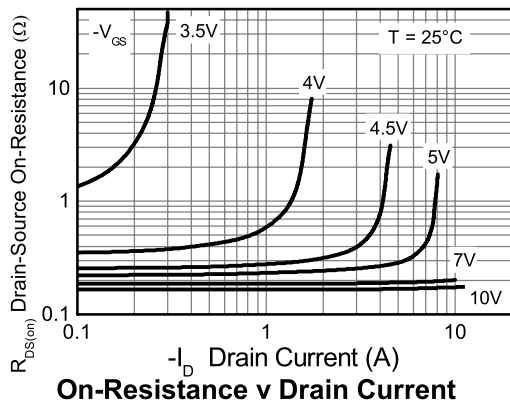
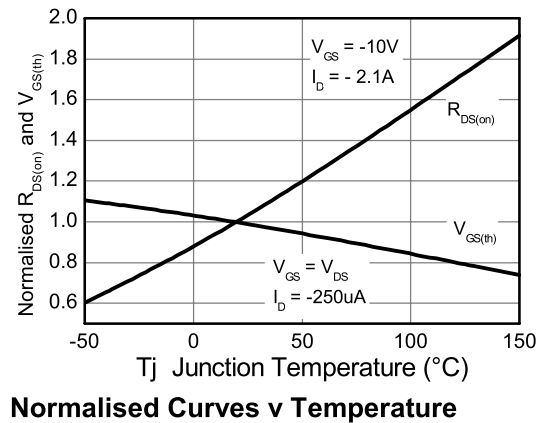
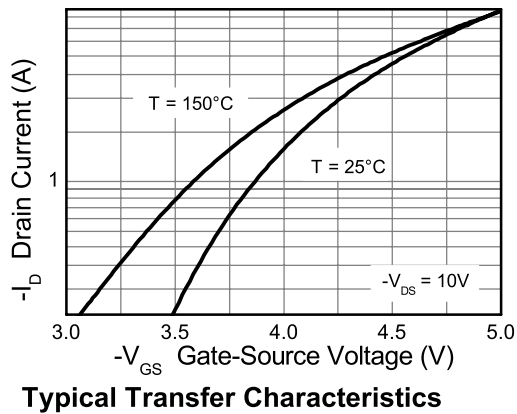
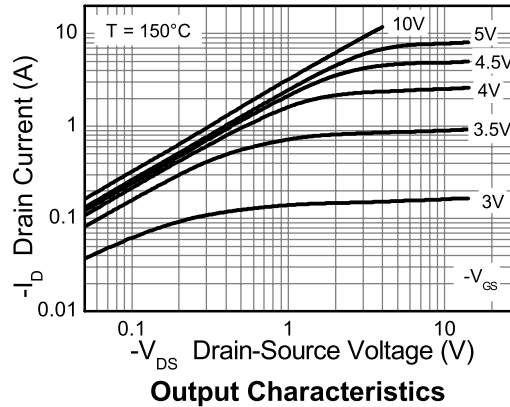
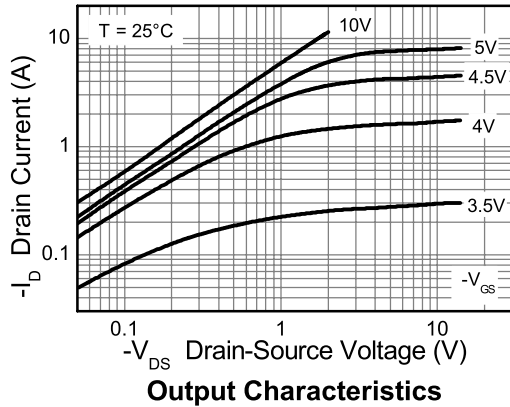
### NOTES:

(\*) Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

(†) Switching characteristics are independent of operating junction temperature.

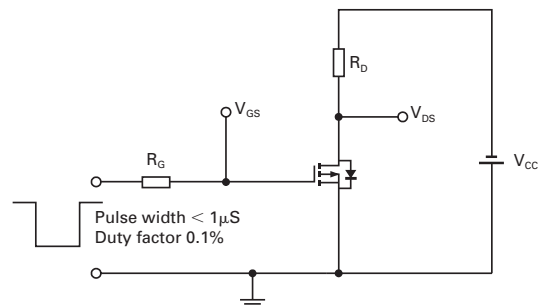
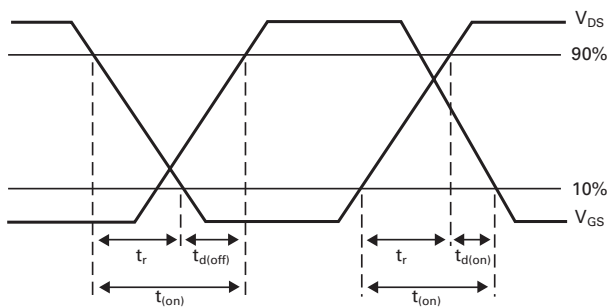
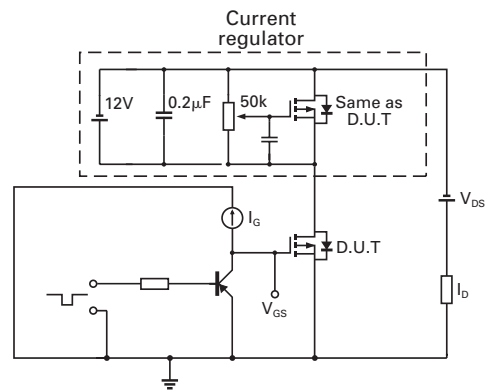
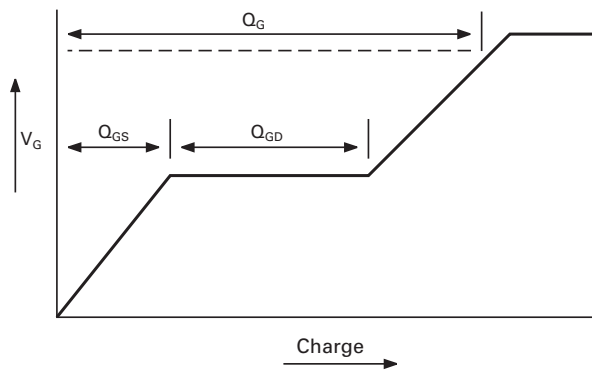
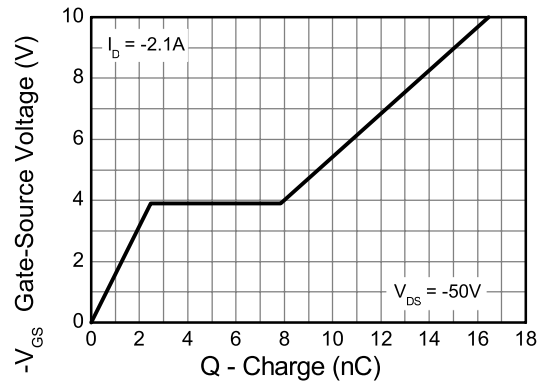
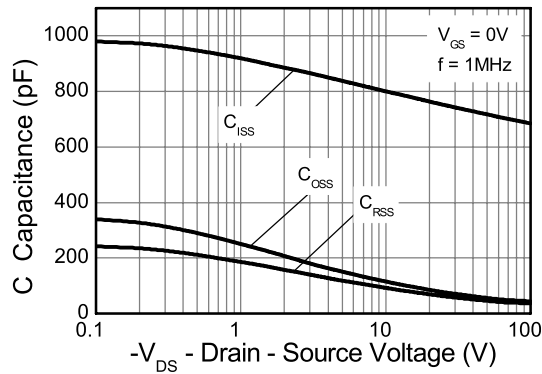
(‡) For design aid only, not subject to production testing.

## Typical characteristics



# ZXMP10A16K

## Typical characteristics

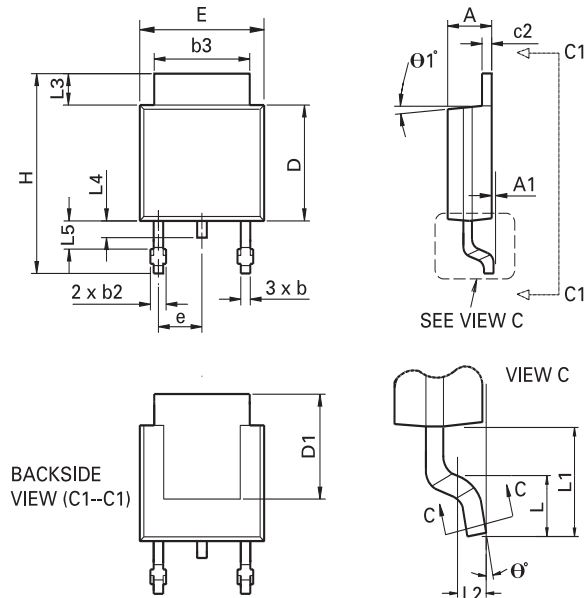


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# ZXMP10A16K

## Package details - DPAK



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.086	0.094	2.18	2.39	e	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	H	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	theta1°	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	theta°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-

**Note:** Controlling dimensions are in inches. Approximate dimensions are provided in millimeters

Europe	Americas	Asia Pacific	Corporate Headquarters
Zetex GmbH Kustermann-park Balanstraße 59 D-81541 München Germany Telefon: (49) 89 45 49 49 0 Fax: (49) 89 45 49 49 49 europe.sales@zetex.com	Zetex Inc 700 Veterans Memorial Highway Hauppauge, NY 11788 USA Telephone: (1) 631 360 2222 Fax: (1) 631 360 8222 usa.sales@zetex.com	Zetex (Asia Ltd) 3701-04 Metroplaza Tower 1 Hing Fong Road, Kwai Fong Hong Kong Telephone: (852) 26100 611 Fax: (852) 24250 494 asia.sales@zetex.com	Zetex Semiconductors plc Zetex Technology Park, Chadderton Oldham, OL9 9LL United Kingdom Telephone: (44) 161 622 4444 Fax: (44) 161 622 4446 hq@zetex.com

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